

ABSTRACT OF THE DISCLOSURE

A wafer rotating device 1 is provided with at least three rollers 2 rotatably provided about axes arranged at parallel intervals and which rotate over the circumferential surface of a disk-shaped wafer 5, a rotation drive mechanism 3 that rotates and drives at least one of the rollers 2, an interval adjustment mechanism 4 capable of adjusting the dimensions of the intervals of the rollers 2, a load control device 6 that controls the load applied from the rollers 2 to the wafer 5 in the radial direction of the wafer 5 when the wafer 5 is clamped between rollers 2. As a result, a silicon wafer can be rotated without contacting the top and bottom surfaces of the silicon wafer.